

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NOBUMASA NISHIYAMA	03/14/2020
TERUHIRO NAKAMIYA	03/16/2020
SATOSHI NAKAMURA	03/18/2020
HIROSHI MATSUDA	03/16/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	WESTERN DIGITAL TECHNOLOGIES, INC.
<b>Street Address:</b>	5601 GREAT OAKS PARKWAY
<b>City:</b>	SAN JOSE
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95119
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16824269
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	WDA-4171-US
<b>NAME OF SUBMITTER:</b>	BRYAN J. MASSEY
<b>SIGNATURE:</b>	/Bryan J. Massey/
<b>DATE SIGNED:</b>	03/20/2020
<b>Total Attachments: 2</b>	
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source=WDA-4171-US_Assignment#page2.tif	

## ASSIGNMENT FOR PATENT APPLICATION

Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

### MULTILAYER FLEX CIRCUIT WITH NON-PLATED OUTER METAL LAYER

Whereas, Western Digital Technologies, Inc., having a place of business at, 5601 Great Oaks Parkway, San Jose, California 95119, (hereinafter referred to as "WDT"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to WDT, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to WDT, its successors and assigns; and we hereby agree that WDT may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by WDT.

Signed on the date(s) indicated beside my (our) signature(s).

- |    |  |                            |
|----|--|----------------------------|
| 1) | Signature: <u>Nobumasa Nishiyama</u><br>Typed Name: Nobumasa Nishiyama | Date: <u>Mar. 14, 2020</u> |
| 2) | Signature: _____<br>Typed Name: Teruhiro Nakamiya                      | Date: _____                |
| 3) | Signature: _____<br>Typed Name: Satoshi Nakamura                       | Date: _____                |
| 4) | Signature: _____<br>Typed Name: Hiroshi Matsuda                        | Date: _____                |

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Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to WDT, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to WDT, its successors and assigns; and we hereby agree that WDT may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by WDT.

Signed on the date(s) indicated beside my (our) signature(s).

- |    |  |                            |
|----|--|----------------------------|
| 1) | Signature: _____<br>Typed Name: Nobumasa Nishiyama                   | Date: _____                |
| 2) | Signature: <u>Teruhiro Nakamiya</u><br>Typed Name: Teruhiro Nakamiya | Date: <u>Mar. 16, 2020</u> |
| 3) | Signature: <u>Satoshi Nakamura</u><br>Typed Name: Satoshi Nakamura   | Date: <u>Mar. 18, 2020</u> |
| 4) | Signature: <u>Hiroshi Matsuda</u><br>Typed Name: Hiroshi Matsuda     | Date: <u>Mar. 16, 2020</u> |